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PATENT & TRADEMARK OFFICE

2814

PATENT
Atty. Dkt. No. AMAT/3771.P1/DSM/LOW K/JW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Mandal

Serial No.: 10/091,699

Confirmation No.: 7928

Filed: March 4, 2002

For: VERY LOW DIELECTRIC CONSTANT PLASMA ENHANCED CVD FILMS

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§ Group Art Unit: 2814
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§ Examiner: Rao, Steven H.
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BOX NON-FEE AMENDMENT
Commissioner for Patents
Washington, D.C. 20231

CERTIFICATE OF MAILING
37 CFR 1.8
I hereby certify that this correspondence is being deposited on 11/19, 2002 with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.

11/19/02 Kevin M. Zhu
Date Signature

Dear Sir:

RESPONSE TO OFFICE ACTION DATED OCTOBER 2, 2002

In response to the Office Action dated October 2, 2002, having a shortened statutory period for response set to expire on January 2, 2003, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no fee is due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/3771.P1/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

IN THE SPECIFICATION:

Please replace paragraph [0037] with the following paragraph:

[0037] The amount of labile organic groups retained in the deposited silicon/oxygen containing material can be increased by mixing the reactive compounds with non-silicon